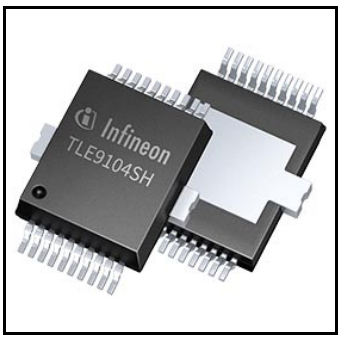
TLE9104SH

Smart Quad Channel Powertrain Switch



1 Overview

Features

- Configurable overcurrent protection
- Overtemperature protection
- Open load detection
- Short circuit to GND detection
- Electrostatic Discharge (ESD) protection
- 16-Bit SPI (for diagnostic and control)
- Soldering: Automated Optical Inspection capability (AOI)
- Green product (completely lead free)
- AEC qualified

Potential applications

The TLE9104SH is best suited for Automotive Powertrain applications. It can be used as driver IC for inductive and ohmic actuators such as injectors, solenoids and relays.

Product validation

Qualified for Automotive Applications. Product Validation according to AEC-Q100/101.

Description

Quad Low-Side Switch in Smart Power Technology (SPT) with four open drain DMOS output stages. The TLE9104SH is protected by embedded protection functions and designed for automotive powertrain applications. The output stages can be controlled directly by parallel inputs for PWM applications (for example gasoline multiport injection) or by SPI.

Type	Package	Marking
TLE9104SH	PG-DSO-20-88	TLE9104SH

Table 1 Product summary

Parameter	Symbol	Value, Unit
Signal supply voltage	V_{IO}	3.0…5.5 V
Analog supply voltage	V_{DD}	4.5…5.5 V
Output clamping voltage	$V_{DS(AZ)}$	50…60 V
Typical On-state resistance CH 1-4 at T_j = 25°C	$R_{DS(ON)}$	150 mΩ
Typical On-state resistance CH 1-4 at T_j = 150°C	$R_{DS(ON)}$	300 mΩ
Nominal load current CH 1-4 (continuous)	I_D	3 A
Short circuit to battery detection threshold CH 1-4	I_{SCB}	5 A

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2 Block diagram

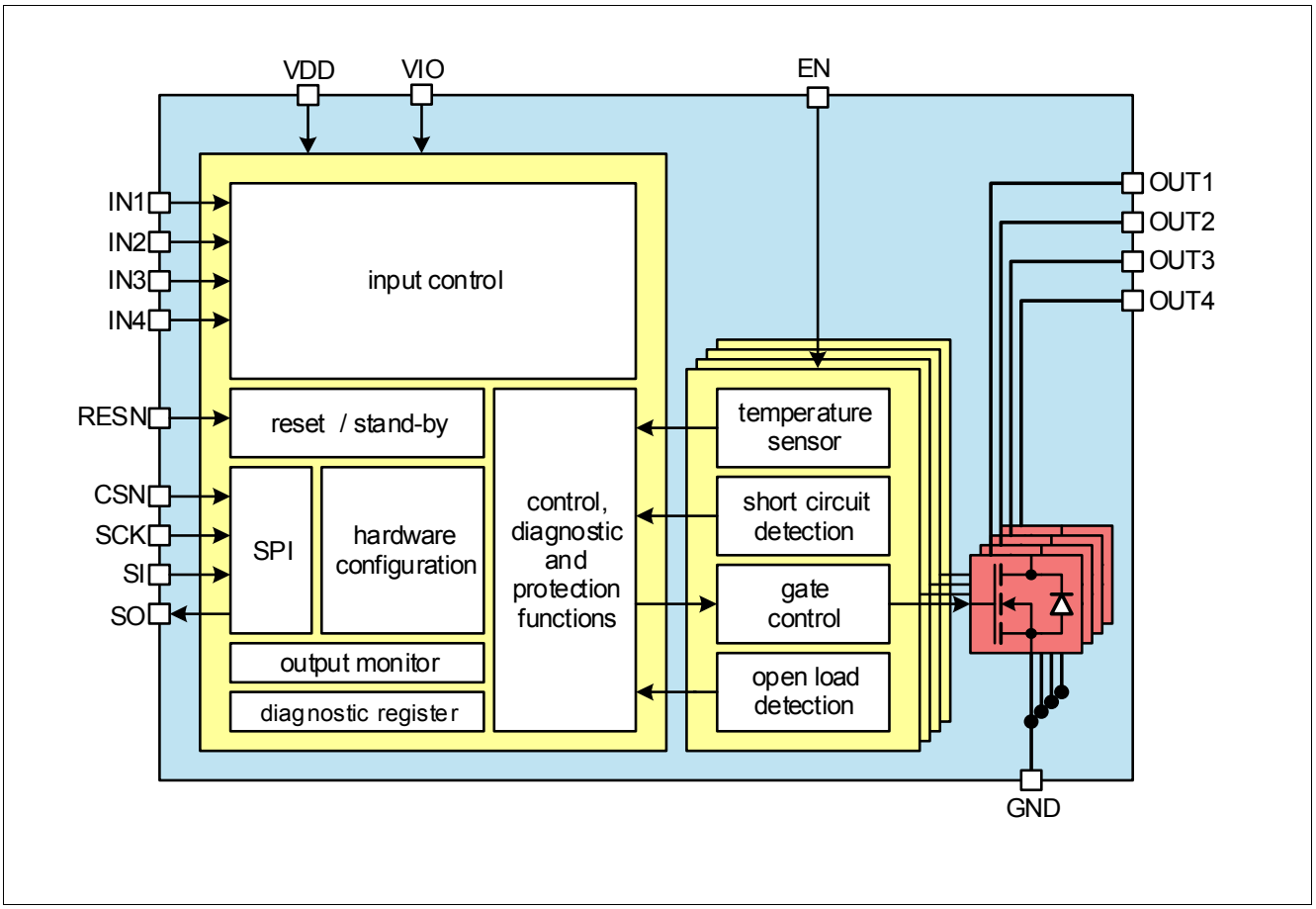


Figure 2-1 Block diagram

3 Pin configuration

3.1 Pin assignment

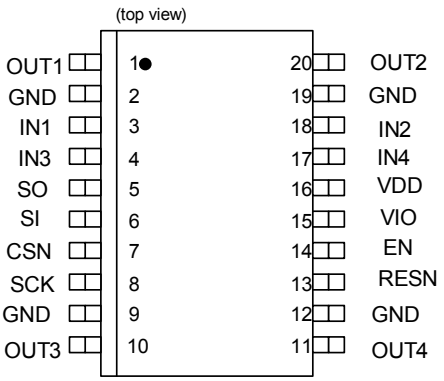


Figure 3-1 Pin configuration (top view)

3.2 Pin definitions and functions

Table 3-1 Pin configuration

#	Pin Name	Function
1	OUT1	Power Output 1
2	GND	Ground
3	IN1	Input 1
4	IN3	Input 3
5	SO	Serial Data Output
6	SI	Serial Data Input
7	CSN	Serial Chip Select (active low)
8	SCK	Serial Clock
9	GND	Ground
10	OUT3	Power Output 3
11	OUT4	Power Output 4
12	GND	Ground
13	RESN	Reset (active low)
14	EN	Output Enable
15	VIO	Signal Supply Voltage
16	VDD	Analog Supply Voltage
17	IN4	Input 4
18	IN2	Input 2
19	GND	Ground
20	OUT2	Power Output 2

Pin configuration

Notes

1. *The exposed pad of TLE9104SH is not connected to ground internally. It is highly recommended to connect the exposed pad to GND pins externally.*
2. *Pins 2 and 19 are the ground pins of outputs 1 and 2 and pins 9 and 12 are the ground pins of outputs 3 and 4. It is highly recommened to connect all GND pins externally.*

4 General product characteristics

4.1 Absolute maximum ratings

Table 4-1 Absolute maximum ratings

T_j = -40°C to +150°C; all voltages with respect to ground, positive current flowing into pin (unless otherwise specified)

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Signal supply voltage	V_{IO}	-0.3	–	5.5	V	–	P_4.1.1
Analog supply voltage	V_{DD}	-0.3	–	5.5	V	–	P_4.1.2
Continuous drain source voltage (OUT1 to OUT4)	V_{DS}	-0.3	–	50	V	–	P_4.1.3
Input voltage, all inputs and data outputs, sense lines	V_{IN}	-0.3	–	V_{IO} + 0.3	V	–	P_4.1.4
Output current per channel[1)]	I_D	0	–	5.5	A	Output ON	P_4.1.5
Maximum voltage for short circuit protection (single event)[2)]	$V_{SC, single}$	–	–	30	V	–	P_4.1.6
Electro**s**tatic **D**ischarge voltage - HBM (human body model)[3)]	V_{ESD1}	-2000	–	2000	V	–	P_4.1.7
Electro**s**tatic **D**ischarge voltage - CDM (charge device model)[4)]	V_{ESD2}	-500	–	500	V	–	P_4.1.8

1) Output current rating as long as maximum junction temperature is not exceeded. The maximum output current in the application must be calculated using R_{thJA} depending on mounting conditions.
2) Short circuit is designed to be short circuit robust according to AEC-Q100-012.
3) According to ANSI/ESDA/JEDEC JS-001.
4) According to JESD22-C101.

Notes

1. *Stresses above the ones listed here may cause permanent damage to the device. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.*
2. *Integrated protection functions are designed to prevent IC destruction under fault conditions described in the data sheet. Fault conditions are considered as “outside” normal operating range. Protection functions are not designed for continuous repetitive operation.*

4.2 Operating conditions

Table 4-2 Operating conditions

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Maximum output clamping energy, linearly decreasing current [1) 2)]	E_{AR}	14	–	–	mJ	$I_{D(0)}$ = 1.4 A, $T_{J(0)}$ = 110°C, Cycles: 1 billion	P_4.2.6
Maximum output clamping energy, linearly decreasing current[3)]	E_{AS}	35	–	–	mJ	T_J = 85°C, Cycles: 10	P_4.2.13
Maximum output clamping energy, linearly decreasing current	E_{AS}	25	–	–	mJ	T_J = 145°C, Cycles: 10	P_4.2.14
Maximum output clamping energy in parallel mode	$E_{AR,p}$	1.7 × E_{AR}	–	–	mJ	OUT1&2 or OUT3&4, $I_{D(0),P}$ = 1.8 × $I_{D(0)}$	P_4.2.2
Thermal resistance							
Junction to case	R_{thJC}	–	1	1.25	K/W	PV = 3 W, homogenously distributed between all output stages	P_4.2.3
Temperature range							
Operating temperature range	T_j	-40	–	150	°C	–	P_4.2.4
Storage temperature range	T_{stg}	-55	–	150	°C	–	P_4.2.5

1) Pulse shape represents inductive switch off: $I_D(t) = I_D(0) \times (1 - t / t_{pulse})$; $0 < t < t_{pulse}$

2) The given energy values are based on a cumulative scenario as specified in the Notes column.

3) The given energy values are based on a cumulative scenario as specified in the Notes column.

Note: Within the functional range, the IC operates as described in the circuit description. The electrical characteristics are specified within the conditions given by the related electrical characteristics table.

5 Electrical and functional description of blocks

5.1 Power supply

The TLE9104SH is supplied by analog power supply line V_{DD} and signal power supply V_{IO}. A capacitor between pins V_{DD} to GND and V_{IO} to GND is recommended. After start-up of the power supply, the RESN pin should be kept low until the Reset Duration Time has expired. This will reset all SPI registers to their default values. In order to enable the output stages the EN pin has to be kept high and OUT_EN register has to be set.

Table 5-1 Electrical characteristics: power supply

V_{DD} = 4.5 V to 5.5 V, V_{IO} = 3 V to 5.5 V, T_j = -40°C to +150°C, (unless otherwise specified)
all voltages with respect to ground, positive current flowing into pin

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Signal supply voltage	V_{IO}	3	–	5.5	V	–	P_5.1.1
Analog supply voltage	V_{DD}	4.5	–	5.5	V	–	P_5.1.2
Supply current	$I_{DD(on)}$	–	–	10	mA	–	P_5.1.3
Input low voltage of pin RESN	$V_{RESN(L)}$	-0.3	–	1	V	–	P_5.1.4
Input high voltage of pin RESN	$V_{RESN(H)}$	2	–	V_{IO} + 0.3	V	–	P_5.1.5
Hysteresis voltage of pin RESN	$V_{RESN(Hys)}$	100	300	500	mV	–	P_5.1.6
Input pull-up current through pin RESN	I_{RESN}	-100	-65	-30	µA	V_{RESET} = 0 V	P_5.1.7
Reset duration time[1)]	$t_{RESN(L)}$	10	–	–	µs	–	P_5.1.8
Input low voltage of pin EN	$V_{EN(L)}$	-0.3	–	1	V	–	P_5.1.9
Input high voltage of pin EN	$V_{EN(H)}$	2	–	V_{IO} + 0.3	V	–	P_5.1.10
Hysteresis voltage of pin EN	$V_{EN(Hys)}$	100	300	500	mV	–	P_5.1.11
Input pull-down current through pin EN	I_{EN}	30	65	100	µA	V_{EN} = 2 V	P_5.1.12

1) For proper startup, after the supply V_{DD} has reached its final voltage, the RESN pin should be held low until the reset duration time has expired.

5.2 Parallel inputs

Each input signal controls the output stage of its related channel. For example, IN1 controls OUT1, IN2 controls OUT2 etc. Input signals are active low. Hence, applying a voltage less than $V_{IN(L)}$ to INx turns OUTx on. It is possible to connect OUT1-2 and OUT3-4 in parallel. For this purpose the right configuration has to be selected in the CFG register. In this case IN1 controls OUT1-2 and IN3 controls OUT3-4.

Table 5-2 Electrical characteristics: parallel inputs

V_{DD} = 4.5 V to 5.5 V, V_{IO} = 3 V to 5.5 V, T_j = -40°C to +150°C, (unless otherwise specified)
all voltages with respect to ground, positive current flowing into pin (unless for pin SO)

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Input low voltage of pin INx	$V_{IN(L)}$	-0.3	–	1	V	–	P_5.2.1
Input high voltage of pin INx	$V_{IN(H)}$	2	–	V_{IO} + 0.3	V	–	P_5.2.2
Input voltage hysteresis	$V_{IN(Hys)}$	100	300	500	mV	–	P_5.2.3
Input pull-up current through pin INx	$I_{IN(L)}$	-100	-65	-30	µA	V_{IN} = 0 V	P_5.2.4

5.3 Power stages

Table 5-3 Electrical characteristics: power outputs

V_{DD} = 4.5 V to 5.5 V, V_{IO} = 3 V to 5.5 V, T_j = -40°C to +150°C, (unless otherwise specified)
all voltages with respect to ground, positive current flowing into pin (unless for pin SO)

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
ON resistance	$R_{DS(ON)}$	–	150		mΩ	T_J = 25°C,	P_5.3.1
ON resistance	$R_{DS(ON)}$	–	300	350	mΩ	T_J = 150°C,	P_5.3.2
ON resistance in parallel mode	$R_{DS(ON)}$	–	75	–	mΩ	T_J = 25°C, outputs 1&2 or 3&4 in parallel	P_5.3.3
ON resistance in parallel mode	$R_{DS(ON)}$	–	150	175	mΩ	T_J = 150°C, outputs 1&2 or 3&4 in parallel	P_5.3.4
Output clamping voltage	$V_{DS(AZ)}$	50	–	60	V	output OFF	P_5.3.5
Output leakage current	$I_{D(lkg)}$	–	–	10	µA	RESN=0	P_5.3.6
Output off-state current	I_{OUTx_OFF}	–	–	30	µA	RESN=1, OUTx_DIAG_EN =0, V_{OUTx} = 35 V	P_5.3.6
Turn-on time	t_{ON}	–	15	–	µs	from 50% of INx to 20% of Vbat	P_5.3.7

Table 5-3 Electrical characteristics: power outputs (cont'd)

V_{DD} = 4.5 V to 5.5 V, V_{IO} = 3 V to 5.5 V, T_j = -40°C to +150°C, (unless otherwise specified)
all voltages with respect to ground, positive current flowing into pin (unless for pin SO)

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Turn-off time	t_{OFF}	–	15	–	µs	from 50% of INx to 80% of Vbat	P_5.3.8
Overtemperature shutdown threshold	$T_{j(OT)}$	165	–	200	°C	–	P_5.3.9

5.4 Protection functions

The TLE9104SH provides embedded protection functions. Integrated protection functions are designed to prevent IC destruction under fault conditions. Fault conditions are considered “outside” the normal operating range. Protection functions are not designed for continuous repetitive operation. Following protection functions are implemented for TLE9104SH:

- Overtemperature protection (OT).
- Short circuit to battery protection (SCB).
- Overcurrent protection (OC).

Note: Integrated protection functions are designed to prevent IC destruction under fault conditions described in the data sheet. Fault conditions are considered as “outside” normal operating range. Protection functions are not designed for continuous repetitive operation.

5.4.1 Overtemperature protection

A dedicated temperature sensor for each channel detects if the temperature of its channel exceeds the overtemperature shutdown threshold. If the channel temperature exceeds the overtemperature shutdown threshold, the overheated channel is switched off immediately to prevent destruction. The channel can be turned on again after clearing the overtemperature error; however, if the sensed temperature is still higher than the overtemperature shutdown threshold the channel will switch off after the filter time t_{OT}.

5.4.2 Short circuit to battery protection

The TLE9104SH is protected in case of short circuit to battery. If the current of an output channel exceeds I_{SCB}, the respective channel is switched off immediately. The channel can be turned on again after the fault condition has been removed and the error has been cleared.

5.4.3 Overcurrent protections

The TLE9104SH is protected with configurable overcurrent protection. If the current of an output channel exceeds I_{OC}, the respective channel is switched off after the filter time $t_{d(OC)}$. The channel can be turned on again after the fault condition has been removed and the error has been cleared. Both current limit threshold I_{OC} and its filter time $t_{d(OC)}$ are configurable via SPI. The filter time, $t_{d(OC)}$, and the current limit threshold, I_{OC}, can only be configured while the output bit, OUT_EN, is low in the SPI register.

5.5 Diagnostic functions

Following diagnosis functions are implemented for all output stages of TLE9104SH:

- Short to battery detection (SCB) can be detected if stages are turned on.
- Overtemperature detection (OT) can be detected if stages are turned on.
- Time based overcurrent detection (OCF) can be detected if stages are turned on.
- Temperature based overcurrent detection (OCT) can be detected if stages are turned on.
- Short to GND detection (SCG) can be detected if stages are turned off.
- Open load detection (OL) can be detected if stages are turned off.

The diagnosis information of TLE9104SH can be accessed via SPI interface. OL and SCG diagnosis are recognized using two thresholds ($V_{OUTn\text{-}SCG}$ and $V_{OUTn\text{-}OL}$). It is also possible to turn off the internal diagnostic pull-down and pull-up current sources. In this case diagnosis of OL and SCG are deactivated.

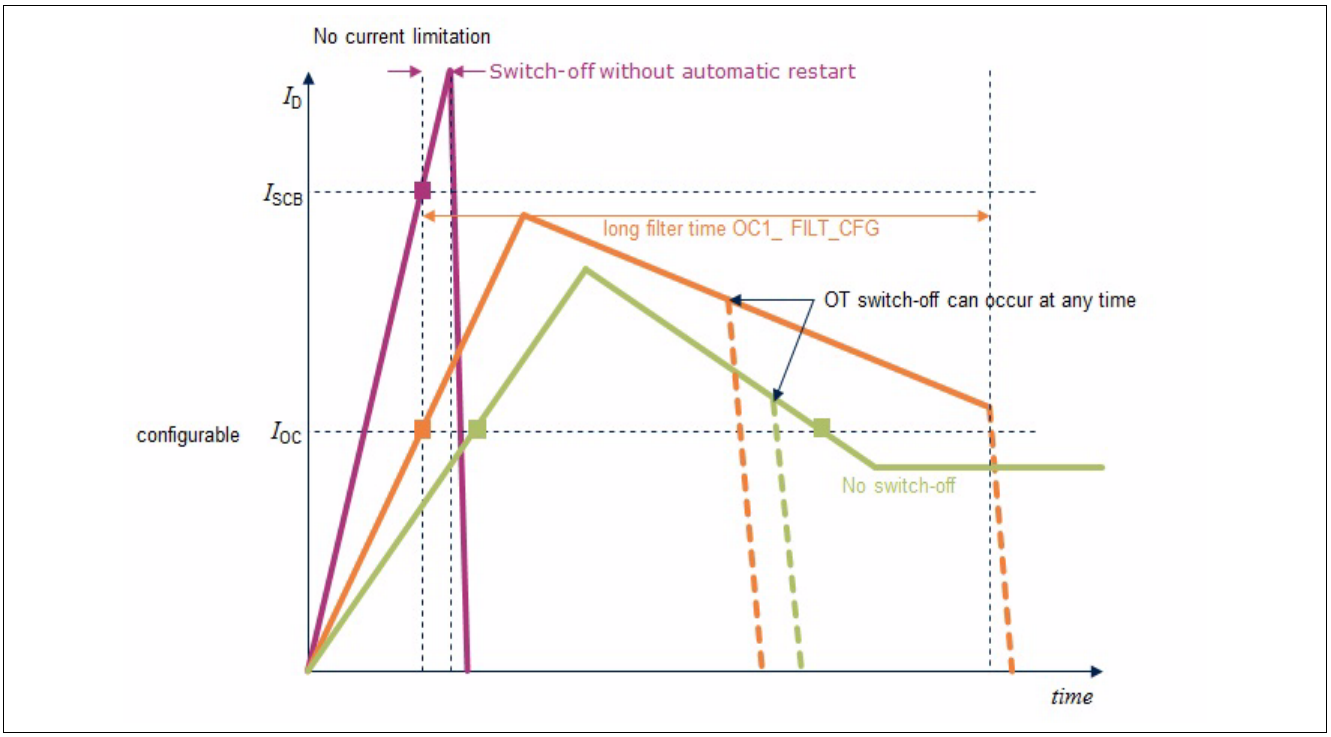


Figure 5-1 Overcurrent and short circuit to battery protection

The fault conditions SCG and OL will not be stored until an integrated filtering time, $t_{d(fault)}$, has expired. An additional blanking time, $t_{b(fault)}$, can be configured in addition to the filter time.The blanking time, $t_{b(fault)}$, can only be configured while output enable bit, OUT_EN, is low in the SPI register.

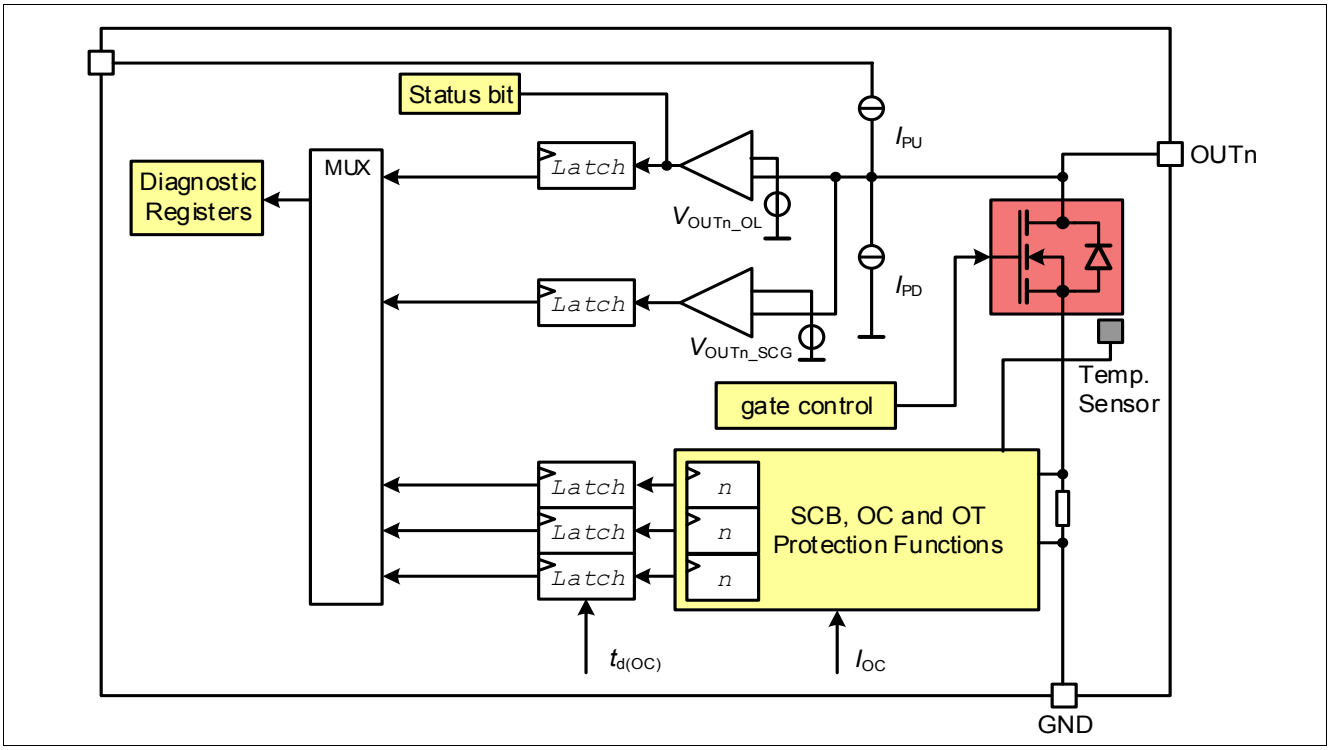


Figure 5-2 Diagnostic functions (overview only)

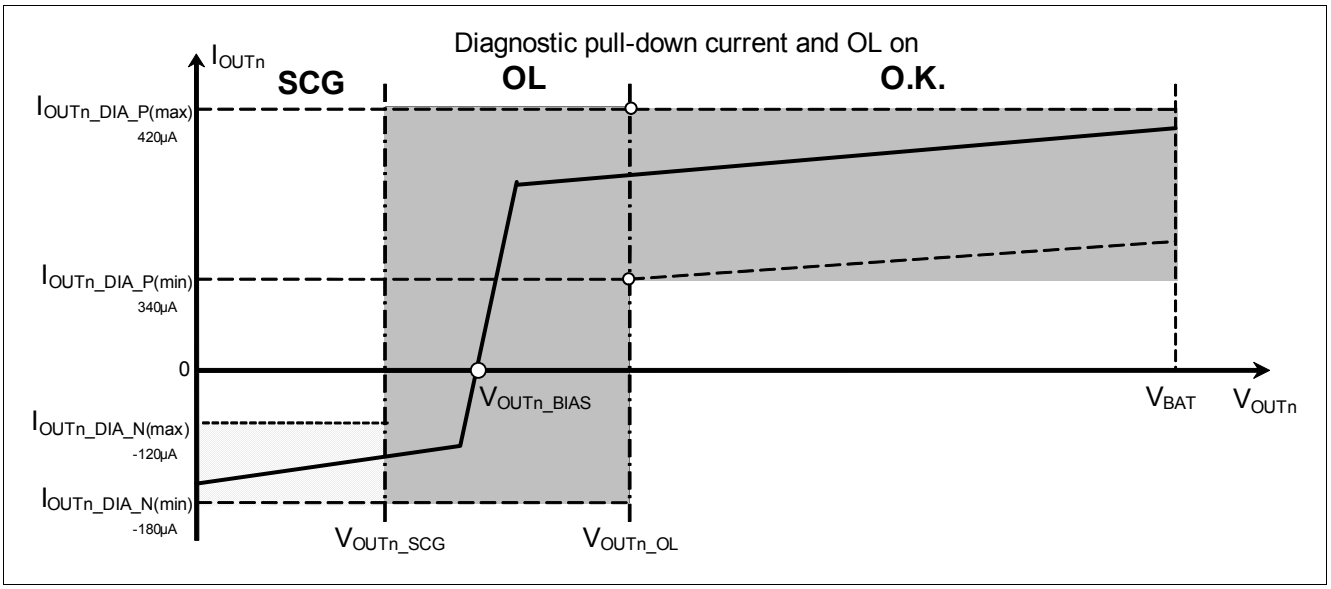


Figure 5-3 SCG and OL diagnostic function (overview only)

Table 5-4 Electrical characteristics: diagnostic functions

V_{DD} = 4.5 V to 5.5 V, V_{IO} = 3 V to 5.5 V, T_j = -40°C to +150°C, (unless otherwise specified)
all voltages with respect to ground, positive current flowing into pin (unless for pin SO)

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Open load detection voltage	$V_{OUTn-OL}$	0.6 V_{DD} - 0.2	–	0.6 V_{DD} + 0.2	V	–	P_5.5.1
Diagnostic pull-down current	I_{PD}	300	380	450	µA	V_{OUTn} = 0.6 V_{DD}	P_5.5.2
Diagnostic pull-up current	I_{PU}	-180	-150	-120	µA	V_{OUTn} = 0.4 V_{DD}	P_5.5.3
Short circuit to ground detection voltage	$V_{OUTn-SCG}$	0.4 V_{DD} - 0.2	–	0.4 V_{DD} + 0.2	V	–	P_5.5.4
Short circuit to battery detection current	I_{SCB}	4.5	5	5.5	A	–	P_5.5.5
Short circuit to battery detection current in parallel mode	I_{SCB}	9	10	11	A	Outputs 1&2 or outputs 3&4 connected in parallel	P_5.5.6
Fault filtering time[1)]	$t_{d(fault)}$	0.015	0.02	0.025	ms		P_5.5.7
Fault blanking time[2)]	$t_{b(fault)}$	0.16	0.2	0.24	ms	configurable via SPI	P_5.5.8
Fault blanking time	$t_{b(fault)}$	0.4	0.5	0.60	ms	default value	P_5.5.9
Fault blanking time	$t_{b(fault)}$	0.8	1	1.2	ms	configurable via SPI	P_5.5.10
Fault blanking time	$t_{b(fault)}$	1.6	2	2.4	ms	configurable via SPI	P_5.5.11
Overcurrent filtering time	$t_{d(OC)}$	0.04	0.06	0.08	ms	default value	P_5.5.12
Overcurrent filtering time	$t_{d(OC)}$	0.1	0.12	0.14	ms	configurable via SPI	P_5.5.13
Overcurrent filtering time	$t_{d(OC)}$	0.4	0.5	0.6	ms	configurable via SPI	P_5.5.14

Table 5-4 Electrical characteristics: diagnostic functions (cont'd)

V_{DD} = 4.5 V to 5.5 V, V_{IO} = 3 V to 5.5 V, T_j = -40°C to +150°C, (unless otherwise specified)
all voltages with respect to ground, positive current flowing into pin (unless for pin SO)

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Overcurrent filtering time	$t_{d(OC)}$	0.8	1	1.2	ms	configurable via SPI	P_5.5.15
Overcurrent filtering time	$t_{d(OC)}$	4	5	6	ms	configurable via SPI	P_5.5.16
Overcurrent filtering time	$t_{d(OC)}$	8	10	12	ms	configurable via SPI	P_5.5.17
Overcurrent filtering time	$t_{d(OC)}$	16	20	24	ms	configurable via SPI	P_5.5.18
Overcurrent filtering time	$t_{d(OC)}$	24	30	36	ms	configurable via SPI	P_5.5.19
Overcurrent threshold	I_{OC}	0.75	1	1.25	A	configurable via SPI	P_5.5.20
Overcurrent threshold	I_{OC}	1.75	2	2.25	A	default value	P_5.5.21
Overcurrent threshold	I_{OC}	2.5	3	3.5	A	configurable via SPI	P_5.5.22
Overcurrent threshold	I_{OC}	3.5	4	4.5	A	configurable via SPI	P_5.5.23
Overcurrent threshold in parallel mode	I_{OC}	1.35	2	2.5	A	configurable via SPI, outputs 1&2 or outputs 3&4 connected in parallel	P_5.5.24
Overcurrent threshold in parallel mode	I_{OC}	3.15	4	4.5	A	default value, outputs 1&2 or outputs 3&4 connected in parallel	P_5.5.25
Overcurrent threshold in parallel mode	I_{OC}	4.5	6	7	A	configurable via SPI, outputs 1&2 or outputs 3&4 connected in parallel	P_5.5.26
Overcurrent threshold in parallel mode	I_{OC}	6.3	8	9	A	configurable via SPI, outputs 1&2 or outputs 3&4 connected in parallel	P_5.5.27
Overtemperature filter time	t_{OT}	2	3	4	µs	–	P_5.5.28
Short circuit to battery filter time	t_{SCB}	1.2	–	2	µs	–	P_5.5.28

1) $t_{d(fault)}$ is the filter time for open load and short to ground diagnostic functions.
2) $t_{d(fault)}$ is the blanking time for open load and short to ground diagnostic functions.

5.5.1 Output stage status

The output of open-load comparator of each channel is directly available via OUTx_STAT bit. This bit can be used to detect a failure condition in which the channel is turned on by INx or SPI but the power stage remains switched off. The delay between a turn on via INx or SPI and a change in status bit depends on the output voltage slew rates and hence on the load itself.

5.6 Communication watchdog

The TLE9104SH is using the watchdog principle to monitor the SPI communication. In case of no communication or continuous communication failures all outputs are disabled. In case of a faulty SPI frame the CWD timer does not retrigger and after the filter time the register CWD-TO is set and can be read as soon as the SPI is back to normal operation. The watchdog is active by default; however, it can be deactivated via a SPI command.

The watchdog starts to work as soon as the device has finished start-up and all blocks are released from reset. If these conditions are met, the watchdog timer t_{CWD} is started. Each correct SPI communication restarts the t_{CWD} timer. If no valid communication is received within timeout, the t_{CWD} timer will expire and disable all outputs. For re-enabling, one needs to clear the error and enable outputs via SPI. Outputs will not be enabled automatically by clearing the error.

The watchdog timer t_{CWD} is configurable via SPI. The watchdog timer t_{CWD} can only be configured while the output enable bit, OUT_EN, is low in the SPI register.

Following SPI communication issues are detected as failure by the watchdog:

- No communication
- Wrong commands
- Frames not equal to 16 clocks

Table 5-5 Communication watchdog timeout configuration

V_{DD} = 4.5 V to 5.5 V, V_{IO} = 3 V to 5.5 V, T_j = -40°C to +150°C, (unless otherwise specified)
all voltages with respect to ground, positive current flowing into pin (unless for pin SO)

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Communication watchdog timeout	t_{CWD0}	20	25	30	ms	configurable via SPI	P_5.6.1
Communication watchdog timeout	t_{CWD1}	40	50	60	ms	default value	P_5.6.2
Communication watchdog timeout	t_{CWD2}	60	75	90	ms	configurable via SPI	P_5.6.3

6 16 bit SPI interface

The diagnostic and control interface is based on a serial peripheral interface (SPI).

The SPI is a full duplex synchronous serial slave interface, which uses four lines: SO, SI, SCK, CSN. Data is transferred by the lines SI and SO at the data rate given by SCK. The falling edge of CSN indicated the beginning of a data access. Data is sampled in on line SI at the falling edge of SCK and shifted out on line SO at the rising edge of SCK. Each access shall be terminated by a rising edge of CSN. A modulo 16 counter ensures that data is taken only, when a multiple of 16 bits has been transferred.

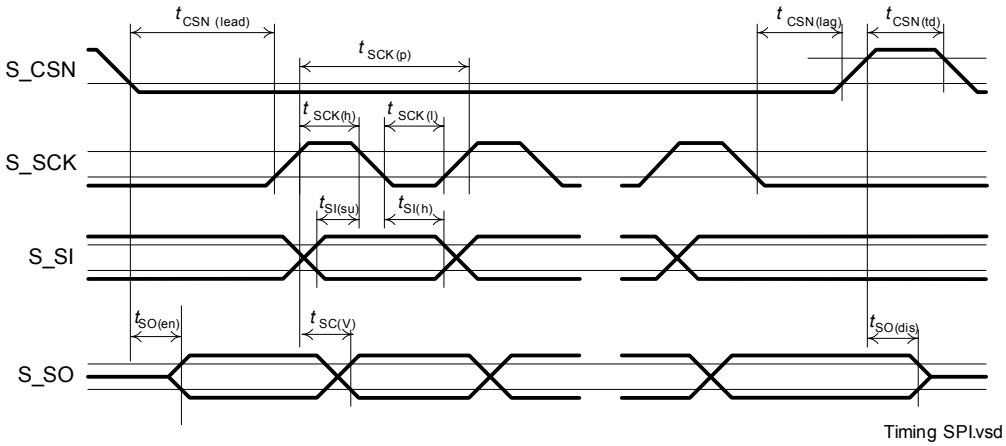


Figure 6-1 SPI timing

6.1 Electrical characteristics 16 bit SPI interface

Table 6-1 Electrical characteristics: 16 bit SPI interface

V_{DD} = 4.5 V to 5.5 V, V_{IO} = 3 V to 5.5 V, T_j = -40°C to +150°C, all voltages with respect to ground, positive current flowing into pin (unless otherwise specified)

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Input characteristics (CSN, SCK, SI)							
L level of pin CSN, SCK, SI	V_{IO_CSNL} V_{IO_SCKL} V_{IO_SIL}	-0.3	–	1	V	–	P_6.1.1
H level of pin CSN, SCK, SI	V_{IO_CSNH} V_{IO_SCKH} V_{IO_SIH}	2	–	V_{IO} + 0.3	V	–	P_6.1.2
Hysteresis input pins	V_{IO_CSNHy} V_{IO_SCKHy} V_{IO_SIHy}	100	300	500	mV	–	P_6.1.3
Output characteristics (SO)							
L level output voltage	V_{IO_SOL}	0	–	1	V	I_{IO_SO} = -2 mA	P_6.1.4
H level output voltage	V_{IO_SOH}	V_{IO} - 0.5	–	V_{IO} + 0.3	–	–	P_6.1.5
Output tristate leakage current	I_{IO_SOoff}	-10	–	10	µA	–	P_6.1.6

Table 6-1 Electrical characteristics: 16 bit SPI interface

V_{DD} = 4.5 V to 5.5 V, V_{IO} = 3 V to 5.5 V, T_j = -40°C to +150°C, all voltages with respect to ground, positive current flowing into pin (unless otherwise specified)

Parameter	Symbol	Values			Unit	Note or Test Condition	Number
		Min.	Typ.	Max.			
Input capacitance							
For CSN, SCK, SI and SO	C_{in}	–	6	8	pF	–	P_6.1.13
Timings							
Serial clock frequency[1)]	f_{SCK}	0	–	8	MHz	C_L = 25 pF	P_6.1.7
Serial clock period	$t_{SCK(P)}$	125	–	–	ns	–	P_6.1.8
Serial clock high time	$t_{SCK(h)}$	50	–	–	ns	–	P_6.1.9
Serial clock low time	$t_{SCK(l)}$	50	–	–	ns	–	P_6.1.10
Enable lead time (falling CSN to rising SCK)	$t_{CSN(lead)}$	250	–	–	ns	–	P_6.1.11
Enable lag time (falling SCK to rising CSN)	$t_{CSN(lag)}$	250	–	–	ns	–	P_6.1.12
Data setup time (required time SI to falling SCK)	$t_{SI(su)}$	20	–	–	ns	–	P_6.1.14
Data hold time (falling SCK to SI)	$t_{SI(h)}$	20	–	–	ns		P_6.1.15
Output enable time (falling CSN to SO valid)	$t_{SO(en)}$	–	–	200	ns	C_L = 25 pF	P_6.1.16
Output disable time (rising CSN to SO tri-state)	$t_{SO(dis)}$	–	–	200	ns	C_L = 25 pF	P_6.1.17
Output data valid time with capacitive load	$t_{SO(v)}$	–	–	100	ns	C_L = 25 pF	P_6.1.18
Transfer delay time (rising CSN to falling CSN)	$t_{CSN(td)}$	1	–	100	µs	C_L = 25 pF	P_6.1.19

1) Maximum SPI clock frequency in the application may be less depending on the load at the SO pin and the microcontroller SPI peripheral timing requirements.

6.2 SPI registers

The general SPI frame length is fixed at 16 bits. Bits 0 to 7 of each frame are used as data frame, bits 8 to 10 are used for address, bit 14 is the parity bit and bit 15 is used to specify a command as read or write. The parity bit is defined as:

$$b_{14} = (1 + b_{15} + \sum_{i=0}^{13} b_i) \bmod 2 \tag{6.1}$$

MOSI

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
R/W	**Parity**	**0**	**0**	**Address**				**Data**							

MISO

15	14	13	12	11	10	9	8	7	6	5	4	3	2	1	0
R/W	**Parity**	**Fault Communi-cation**	**Fault Global**	**Address**				**Data**							

IN MOSI and MISO a read is defined with a ‘0’ and a write is defined with a ‘1’. Each MISO SPI frame reports the important system faults as Global or Communication faults in bit 12 and 13 as following:

- Global fault is asserted (not latching) when the general fault bit in Global_Status register is set.
- Communication fault is asserted (not latching) when one of the following faults are present:
  - Communication error (the same as COM_ERR in Global_Status register)
  - Communication watchdog timeout
  - Parity error

Besides, global status register stores the faults as following:

- General fault if at least one of the following faults are present:
  - Over-current
  - Over-temperature
  - Over-temperature during overcurrent
  - Short circuit to battery
  - Open load
  - Short circuit to ground
- Communication error:
  - No communication
  - Wrong command
  - Frames not equal to 16 bits
- Parity error
- Communication watchdog

16 bit SPI interface

Apart from the faults, global register also restores the enable latch signal (EN_Latch) and power on reset latch (POR_Latch) as following:

- EN_Latch: This bit has a reset value of ‘0’. After setting the OUT_EN bit this bit changes to ‘1’. This bit shows whether the output has been enabled (via SPI) at least once since the last clear.
- POR_Latch: This bit has a reset value of ‘1’. It can be changed to ‘0’ via SPI. Any power on reset will set the bit back to 1. This can be used to check whether a power on reset has happened since the bit value was changed to ‘0’.

Table 6-2 Register Address Space

Module	Base Address	End Address	Note
apb	0_H	$1F_H$	–

Table 6-3 Register Overview

Register Short Name	Register Long Name	Offset Address	Page Number
CTRL	Output control register	00_H	22
CFG	Configuration register	01_H	24
OFF_DIAG_CFG	Off-state diagnostic configuration register	02_H	25
ON_DIAG_CFG	On-state diagnostic configuration register	03_H	26
DIAG_OUT_1_2_ON	On-state diagnostic result register OUT1 & OUT2	04_H	27
DIAG_OUT_3_4_ON	On-state diagnostic result register OUT3 & OUT4	05_H	28
DIAG_OFF	Off-state diagnostic result register	06_H	29
GLOBAL_STATUS	Global device status register	07_H	30
ICVID	IC Version ID	08_H	31

The registers are addressed wordwise.

Table 6-4 Register Overview

Bit type short name	Bit type description	Note
r	read	–
rw	read/write	–
rwc	read and clear on write	clear on write 0

Note: All configurations can only be changed while the OUT_EN bit is cleared.

6.2.1 Registers

Output control register

CTRL	Offset	Reset Value
Output control register	**00_H**	**00_H**

7	6	5	4	3	2	1	0
OUT4_ON_S	OUT4_ON_C	OUT3_ON_S	OUT3_ON_C	OUT2_ON_S	OUT2_ON_C	OUT1_ON_S	OUT1_ON_C
rw	rw	rw	rw	rw	rw	rw	rw

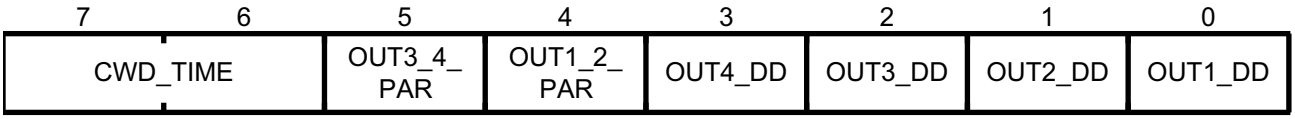
Field	Bits	Type	Description
OUT4_ON_S	7	rw	**OUT4 SPI control bit (used if CFG.OUT4_DD = 0)** 1_D **SET**, Output 4 set 0_D **NO_ACTION**, Output 4 no action Reset: 0_B
OUT4_ON_C	6	rw	**OUT4 SPI control bit (used if CFG.OUT4_DD = 0)** 1_D **CLEAR**, Output 4 clear 0_D **NO_ACTION**, Output 4 no action Reset: 0_B
OUT3_ON_S	5	rw	**OUT3 SPI control bit (used if CFG.OUT3_DD = 0)** 1_D **SET**, Output 3 set 0_D **NO_ACTION**, Output 3 no action Reset: 0_B
OUT3_ON_C	4	rw	**OUT3 SPI control bit (used if CFG.OUT3_DD = 0)** 1_D **CLEAR**, Output 3 clear 0_D **NO_ACTION**, Output 3 no action Reset: 0_B
OUT2_ON_S	3	rw	**OUT2 SPI control bit (used if CFG.OUT2_DD = 0)** 1_D **SET**, Output 2 set 0_D **NO_ACTION**, Output 2 no action Reset: 0_B
OUT2_ON_C	2	rw	**OUT2 SPI control bit (used if CFG.OUT2_DD = 0)** 1_D **CLEAR**, Output 2 clear 0_D **NO_ACTION**, Output 2 no action Reset: 0_B
OUT1_ON_S	1	rw	**OUT1 SPI control bit (used if CFG.OUT1_DD = 0)** 1_D **SET**, Output 1 set 0_D **NO_ACTION**, Output 1 no action Reset: 0_B

Field	Bits	Type	Description
OUT1_ON_C	0	rw	**OUT1 SPI control bit (used if CFG.OUT1_DD = 0)** 1_D **CLEAR**, Output 1 clear 0_D **NO_ACTION**, Output 1 no action Reset: 0_B

16 bit SPI interface

Configuration register

CFG	Offset	Reset Value
Configuration register	**01_H**	**$8F_H$**

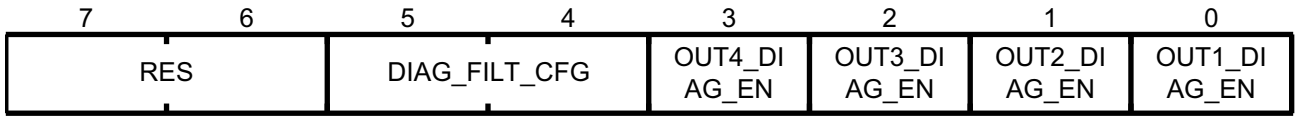


Field	Bits	Type	Description
CWD_TIME	7:6	rw	**Communication watchdog timeout configuration** 3_D **LONG**, 75 ms 2_D **MEDIUM**, 50 ms (default) 1_D **SHORT**, 25 ms 0_D **DISABLED**, Communication watchdog disabled Reset: 10_B
OUT3_4_PAR	5	rw	**OUT3-4 parallel mode** 1_D **ENABLED**, OUT3-4 parallel mode (controlled by IN3 or CTRL.OUT3_ON) 0_D **DISABLED**, OUT3, OUT4 controlled separately (default) Reset: 0_B
OUT1_2_PAR	4	rw	**OUT1-2 parallel mode** 1_D **ENABLED**, OUT1-2 parallel mode (controlled by IN1 or CTRL.OUT1_ON) 0_D **DISABLED**, OUT1, OUT2 controlled separately (default) Reset: 0_B
OUT4_DD	3	rw	**OUT4 direct drive mode** 1_D **ENABLED**, OUT4 controlled by IN4 (default) 0_D **DISABLED**, OUT4 controlled by SPI (CTRL.OUT4_ON) Reset: 1_B
OUT3_DD	2	rw	**OUT3 direct drive mode** 1_D **ENABLED**, OUT3 controlled by IN3 (default) 0_D **DISABLED**, OUT3 controlled by SPI (CTRL.OUT3_ON) Reset: 1_B
OUT2_DD	1	rw	**OUT2 direct drive mode** 1_D **ENABLED**, OUT2 controlled by IN2 (default) 0_D **DISABLED**, OUT2 controlled by SPI (CTRL.OUT2_ON) Reset: 1_B
OUT1_DD	0	rw	**OUT1 direct drive mode** 1_D **ENABLED**, OUT1 controlled by IN1 (default) 0_D **DISABLED**, OUT1 controlled by SPI (CTRL.OUT1_ON) Reset: 1_B

16 bit SPI interface

Off-state diagnostic configuration register

OFF_DIAG_CFG	Offset	Reset Value
Off-state diagnostic configuration register	02_H	$1F_H$

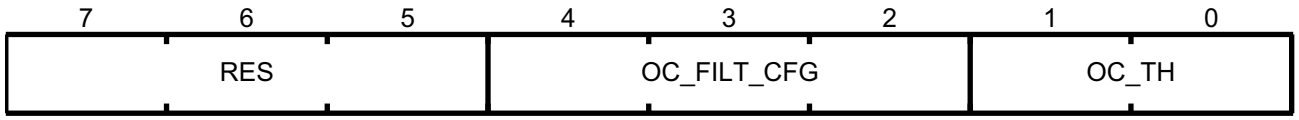


Field	Bits	Type	Description
DIAG_FILT_CFG	5:4	rw	**Diagnostic filter time configuration** 3_D **2000_us**, 2000 us 2_D **1000_us**, 1000 us 1_D **500_us**, 500 us (default) 0_D **200_us**, 200 us Reset: 01_B
OUT4_DIAG_EN	3	rw	**Enable diagnostic current OUT4** 1_D **ON**, Diagnostic current ON (default) 0_D **OFF**, Diagnostic current OFF Reset: 1_B
OUT3_DIAG_EN	2	rw	**Enable diagnostic current OUT3** 1_D **ON**, Diagnostic current ON (default) 0_D **OFF**, Diagnostic current OFF Reset: 1_B
OUT2_DIAG_EN	1	rw	**Enable diagnostic current OUT2** 1_D **ON**, Diagnostic current ON (default) 0_D **OFF**, Diagnostic current OFF Reset: 1_B
OUT1_DIAG_EN	0	rw	**Enable diagnostic current OUT1** 1_D **ON**, Diagnostic current ON (default) 0_D **OFF**, Diagnostic current OFF Reset: 1_B

16 bit SPI interface

On-state diagnostic configuration register

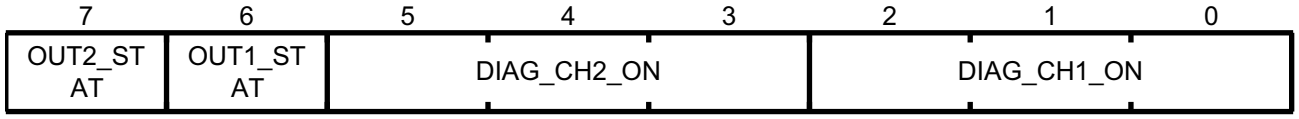
ON_DIAG_CFG	Offset	Reset Value
On-state diagnostic configuration register	03_H	01_H



Field	Bits	Type	Description
OC_FILT_CFG	4:2	rw	**Overcurrent shut-down delay time (for all channels)** 7_D **30_ms**, 30 ms 6_D **20_ms**, 20 ms 5_D **10_ms**, 10 ms 4_D **5_ms**, 5 ms 3_D **1_ms**, 1 ms 2_D **500_us**, 500 us 1_D **120_us**, 120 us 0_D **60_us**, 60 us (default) Reset: 000_B
OC_TH	1:0	rw	**Overcurrent shut-down threshold (for all channels) (d_oc_th)** 3_D **4000_mA**, 4 A 2_D **3000_mA**, 3 1_D **2000_mA**, 2 A (default) 0_D **1000_mA**, 1 A Reset: 01_B

On-state diagnostic result register OUT1 & OUT2

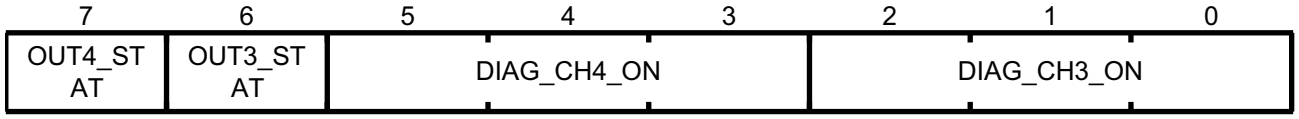
DIAG_OUT_1_2_ON	Offset	Reset Value
On-state diagnostic result register OUT1 & OUT2	**04_H**	**00_H**



Field	Bits	Type	Description
OUT2_STAT	7	r	**Channel 2 output status** 1_D **ON**, Channel is ON 0_D **OFF**, Channel is OFF Reset: 0_B
OUT1_STAT	6	r	**Channel 1 output status** 1_D **ON**, Channel is ON 0_D **OFF**, Channel is OFF Reset: 0_B
DIAG_CH2_ON	5:3	rwc	**On-state diagnostic result register - Channel 2** 7_D **UNUSED**, unused combination 6_D **UNUSED**, unused combination 5_D **OT**, Overtemperature 4_D **OC_TIME**, Overcurrent timeout 3_D **OC_OT**, Overtemperature during overcurrent 2_D **SCB**, Short to battery 1_D **NO_FAIL**, no failure detected 0_D **UNKNOWN**, no diagnosis done Reset: 000_B
DIAG_CH1_ON	2:0	rwc	**On-state diagnostic result register - Channel 1** 7_D **UNUSED**, unused combination 6_D **UNUSED**, unused combination 5_D **OT**, Overtemperature 4_D **OC_TIME**, Overcurrent timeout 3_D **OC_OT**, Overtemperature during overcurrent 2_D **SCB**, Short to battery 1_D **NO_FAIL**, no failure detected 0_D **UNKNOWN**, no diagnosis done Reset: 000_B

On-state diagnostic result register OUT3 & OUT4

DIAG_OUT_3_4_ON	Offset	Reset Value
On-state diagnostic result register OUT3 & OUT4	**05_H**	**00_H**

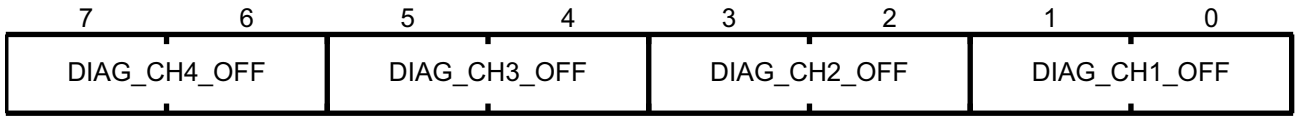


Field	Bits	Type	Description
OUT4_STAT	7	r	**Channel 4 output status** 1_D **ON**, Channel is ON 0_D **OFF**, Channel is OFF Reset: 0_B
OUT3_STAT	6	r	**Channel 3 output status** 1_D **ON**, Channel is ON 0_D **OFF**, Channel is OFF Reset: 0_B
DIAG_CH4_ON	5:3	rwc	**On-state diagnostic result register - Channel 4** 7_D **UNUSED**, unused combination 6_D **UNUSED**, unused combination 5_D **OT**, Overtemperature 4_D **OC_TIME**, Overcurrent timeout 3_D **OC_OT**, Overtemperature during overcurrent 2_D **SCB**, Short to battery 1_D **NO_FAIL**, no failure detected 0_D **UNKNOWN**, no diagnosis done Reset: 000_B
DIAG_CH3_ON	2:0	rwc	**On-state diagnostic result register - Channel 3** 7_D **UNUSED**, unused combination 6_D **UNUSED**, unused combination 5_D **OT**, Overtemperature 4_D **OC_TIME**, Overcurrent timeout 3_D **OC_OT**, Overtemperature during overcurrent 2_D **SCB**, Short to battery 1_D **NO_FAIL**, no failure detected 0_D **UNKNOWN**, no diagnosis done Reset: 000_B

16 bit SPI interface

Off-state diagnostic result register

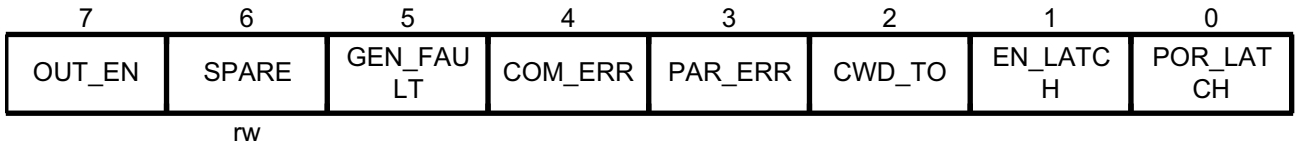
DIAG_OFF	Offset	Reset Value
Off-state diagnostic result register	06_H	00_H



Field	Bits	Type	Description
DIAG_CH4_OFF	7:6	rwc	**OFF-state diagnostic result register Channel 4** 3_D **SCG**, Short to ground 2_D **OL**, Open load 1_D **NO_FAIL**, no failure detected 0_D **UNKNOWN**, no diagnosis done Reset: 00_B
DIAG_CH3_OFF	5:4	rwc	**Off-state diagnostic result register Channel 3** 3_D **SCG**, Short to ground 2_D **OL**, Open load 1_D **NO_FAIL**, no failure detected 0_D **UNKNOWN**, no diagnosis done Reset: 00_B
DIAG_CH2_OFF	3:2	rwc	**Off-state diagnostic result register Channel 2** 3_D **SCG**, Short to ground 2_D **OL**, Open load 1_D **NO_FAIL**, no failure detected 0_D **UNKNOWN**, no diagnosis done Reset: 00_B
DIAG_CH1_OFF	1:0	rwc	**Off-state diagnostic result register Channel 1** 3_D **SCG**, Short to ground 2_D **OL**, Open load 1_D **NO_FAIL**, no failure detected 0_D **UNKNOWN**, no diagnosis done Reset: 00_B

Global device status register

GLOBAL_STATUS	Offset	Reset Value
Global device status register	**07_H**	**01_H**

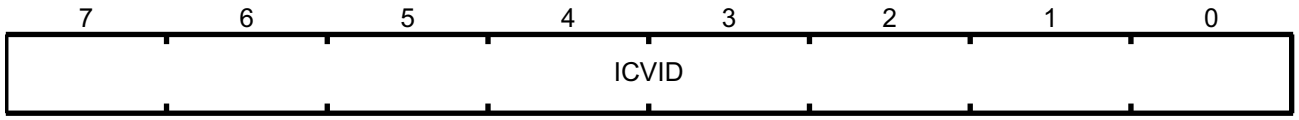


Field	Bits	Type	Description
OUT_EN	7	rw	**OUTx enable bit** 1_D **ENABLED**, Output switching enabled 0_D **DISABLED**, Outputs disabled (default) Reset: 0_B
SPARE	6	rw	**Spare register for future use** 1_D **GLOBAL_STATUS_SPARE_EN**, 0_D **GLOBAL_STATUS_SPARE_DIS**, (default) Reset: 0_B
GEN_FAULT	5	rwc	**General fault flag** 1_D **ERR**, At least one fault was detected 0_D **NO_ERR**, No fault was detected Reset: 0_B
COM_ERR	4	rwc	**Communication Error Flag** 1_D **ERR**, At least one communication failure was detected 0_D **NO_ERR**, No communication failure was detected Reset: 0_B
PAR_ERR	3	rwc	**Parity Error Flag** 1_D **ERR**, At least one parity error was detected 0_D **NO_ERR**, No parity error was detected Reset: 0_B
CWD_TO	2	rwc	**Communication watchdog timeout** 1_D **ERR**, Communication watchdog timeout occurred 0_D **NO_ERR**, No communication watchdog timeout (default) Reset: 0_B
EN_LATCH	1	rwc	**EN Latch** 1_D **EN**, Device was enabled since last read-out 0_D **NO_EN**, Device was not enabled since last cleared Reset: 0_B
POR_LATCH	0	rwc	**Power-on reset latch** 1_D **POR**, Device was reset since last cleared 0_D **NO_POR**, Device was not reset since last cleared Reset: 1_B

16 bit SPI interface

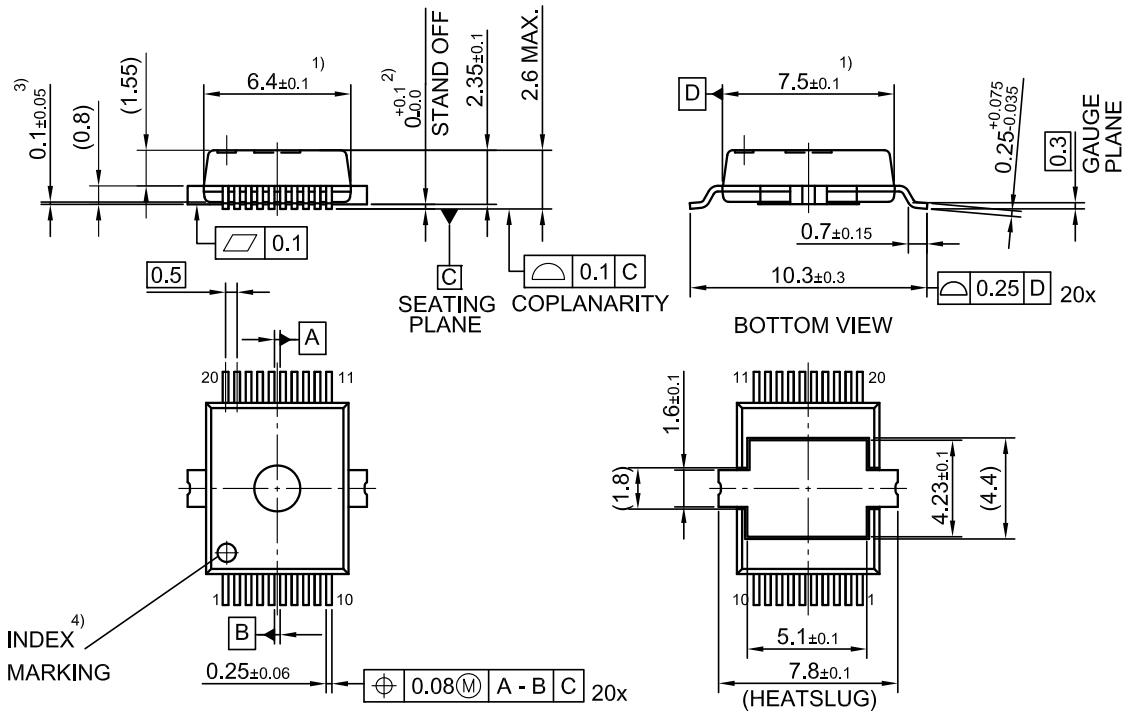
IC Version ID

ICVID	Offset	Reset Value
IC Version ID	08_H	$B1_H$



Field	Bits	Type	Description
ICVID	7:0	r	**IC Version ID** 177_D **ICVID**, Reset: $B1_H$

7 Package outlines



1) DOES NOT INCLUDE PLASTIC OR METAL PROTRUSION OF 0.15 MAX. PER SIDE
2) STAND OFF
3) STAND OUT
4) PIN 1 INDEX MARKING; POLISH FINISH

Figure 7-1 PG-DSO-20-88 (Plastic Dual Small Outline Package) Green Product - Package dimensions are preliminary and may be updated

Green product (RoHS-compliant)

To meet the world-wide customer requirements for environmentally friendly products and to be compliant with government regulations the device is available as a green product. Green products are RoHS-compliant (i.e Pb-free finish on leads and suitable for Pb-free soldering according to IPC/JEDEC J-STD-020).

Floating exposed pad

The exposed pad of TLE9104SH is not connected to the ground internally. It is highly recommended to connect the exposed pad to GND pins externally.

For further information on alternative packages, please visit our website:
http://www.infineon.com/packages.

Dimensions in mm

8 Application information

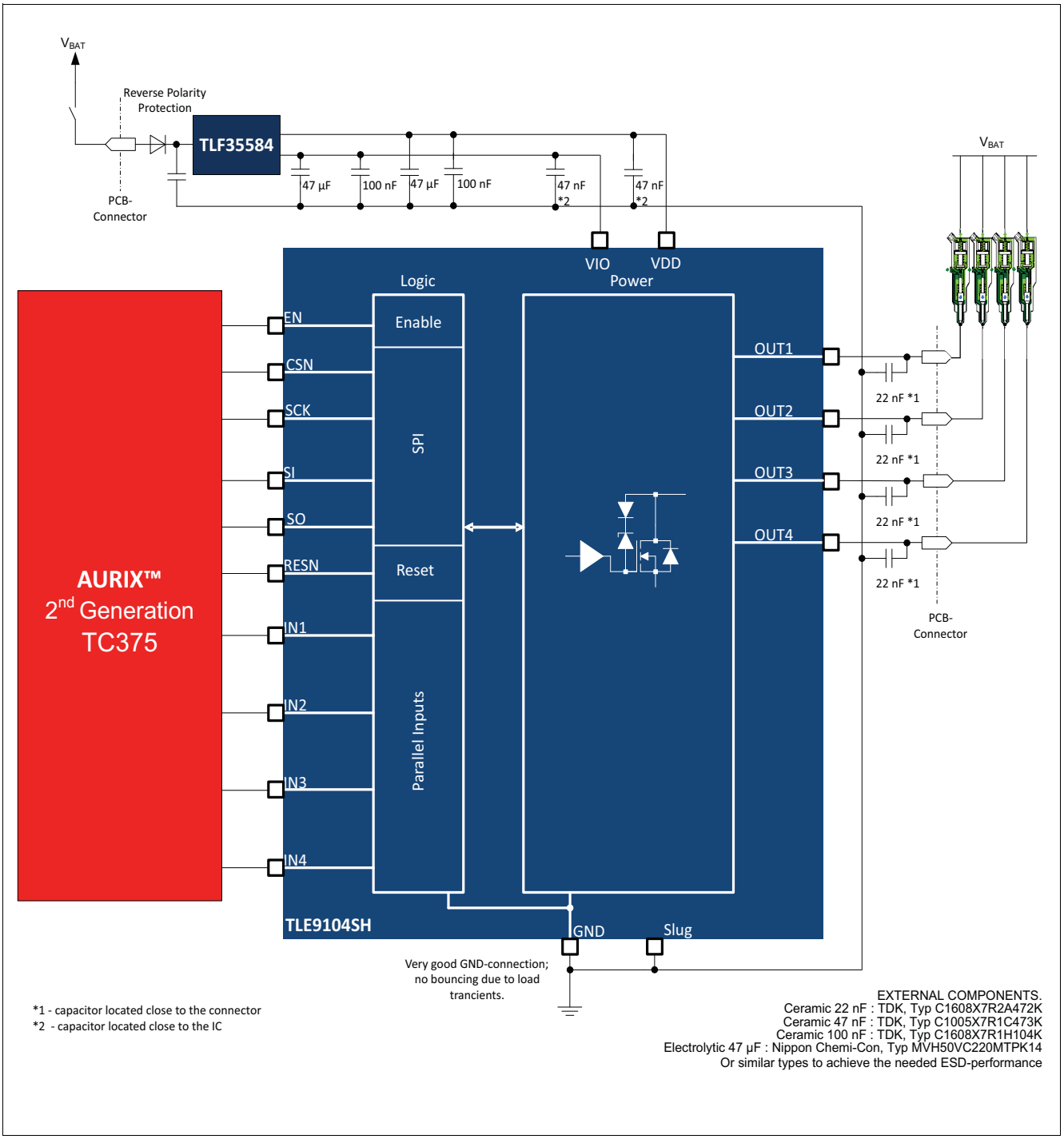


Figure 8-1 Multi port injection application diagram

9 Revision history

Table 9-1 Revision history

Version	Date	Changes
Rev. 1.2	2018-10-26	Changed H level output voltage of SO Pin symbol and minimum value changed
Rev. 1.1	2018-02-15	OC filter times updates in SPI table
Rev. 1.0	2018-02-01	First datasheet release

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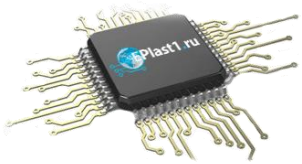
- Подбор аналогов;
- Консультации по применению компонента;
- Поставка образцов и прототипов;
- Техническая поддержка проекта;
- Защита от снятия компонента с производства.



Как с нами связаться

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